## AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

- 1.-10. (cancelled)
- 11. (currently amended) An apparatus comprising:

an electronic component body; and

one or more leads coupled to and extending from the electronic component body,

wherein a first lead of the one or more leads comprises a first leg and a second leg, the first leg and the second leg defining an first acute angle therebetween,

wherein\_the second leg emprises comprising a first portion defining the <u>first</u> acute angle with the first leg, <u>and</u> a second <u>portion defining a second acute angle with the first portion, and a third portion defining a first obtuse angle with the second portion, wherein the third portion is substantially parallel to the first leg, <del>and</del></u>

wherein a length of the <u>secondthird</u> portion that is substantially parallel to the first leg is substantially equal to a thickness of a substrate to which the electronic component body is to be mounted,

wherein a vertex of the first obtuse angle is to abut the substrate, and
wherein the substrate is to be disposed between the vertex and the electronic component
body.

- 12. (cancelled)
- 13. (currently amended) An apparatus according to Claim 11,

the second leg comprising a third fourth portion defining an a second obtuse angle with the second third portion.

# 14. (cancelled)

15. (currently amended) A method comprising:

bending an electronic component body lead to form a first leg and a second leg, the first leg and the second leg defining an first acute angle therebetween; and

bending the second leg to form a first portion defining the <u>first</u> acute angle with the first leg, and a second <u>portion defining a second acute angle with the first portion</u>, and a third portion <u>defining a first obtuse angle with the second portion</u>, wherein the third portion is substantially parallel to the first leg,

wherein a vertex of the first obtuse angle is to abut the substrate,

wherein the substrate is to be disposed between the vertex and the electronic component body, and

wherein a length of the <u>secondthird</u> portion that is substantially parallel to the first leg is substantially equal to a thickness of a substrate to which the electronic component body is to be mounted.

## 16. (cancelled)

17. (currently amended) A method according to Claim 15, further comprising bending the second leg to form a third fourth portion defining an a second obtuse angle with the second third portion.

#### 18. (cancelled)

19. (original) A method according to Claim 15, further comprising: electrically coupling the lead to an electronic component body.

20. (original) A method according to Claim 15, wherein the lead is attached to an electronic component body.

## 21. (currently amended) A method comprising:

placing a lead of an electronic component body into an opening of a substrate, wherein the lead comprises a first leg and a second leg defining an first acute angle therebetween,

wherein the second leg emprises comprising a first portion defining the <u>first</u> acute angle with the first leg, <u>and</u> a second <u>portion defining a second acute angle with the first portion, and a third portion defining a first obtuse angle with the second portion, wherein the third portion is substantially parallel to the first leg, <del>and</del></u>

wherein a vertex of the first obtuse angle is to abut the substrate,

wherein the substrate is to be disposed between the vertex and the electronic component body, and

wherein a length of the <u>secondthird</u> portion that is substantially parallel to the first leg is substantially equal to a thickness of the substrate.

- 22. (cancelled)
- 23. (currently amended) A method according to Claim 21, the second leg comprising a third fourth portion defining an a second obtuse angle with the second third portion.
  - 24. (cancelled)
  - 25. (original) A method according to Claim 21, further comprising: electrically coupling the lead to the substrate.

26. (currently amended) An expansion card comprising:

a circuit board;

a connector coupled to the circuit board, the connector to connect to a motherboard; and an electronic component body coupled to the circuit board, the electronic component body comprising one or more leads coupled to and extending from the electronic component body,

wherein a first lead of the one or more leads comprises a first leg, and a second leg, the first leg and the second leg defining an first acute angle therebetween,

wherein the second leg comprisinges a first portion defining the <u>first</u> acute angle with the first leg, and a second portion defining a second acute angle with the first portion, and a third portion defining a first obtuse angle with the second portion, wherein the third portion is substantially parallel to the first leg, and

wherein a vertex of the first obtuse angle is to abut the substrate,

wherein the substrate is to be disposed between the vertex and the electronic component body, and

wherein a length of the <u>secondthird</u> portion that is substantially parallel to the first leg is substantially equal to a thickness of the circuit board.

## 27. (cancelled)

28. (currently amended) An expansion card according to Claim 26,

the second leg comprising a third-fourth portion defining an a second obtuse angle with the second-third portion.

#### 29. (cancelled)